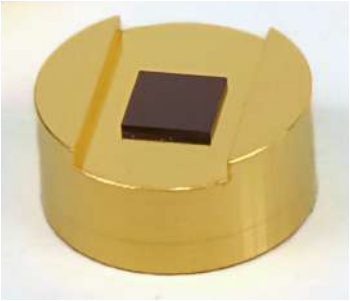
Glued SAM data sheet SAM-λ-A-τ-4.0-12.7g-c or SAM-λ-A-τ-4.0-12.7g-e

SAM chip area	standard:	4.0 mm x 4.0 mm
	optional:	other dimensions on request
Chip thickness	standard:	450 µm
Front side protection	The SAM is protected with a dielectric front layer.	

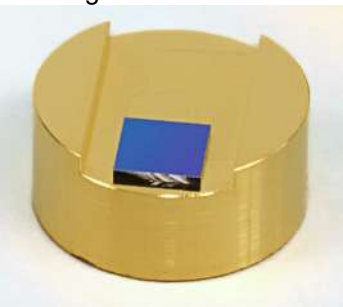
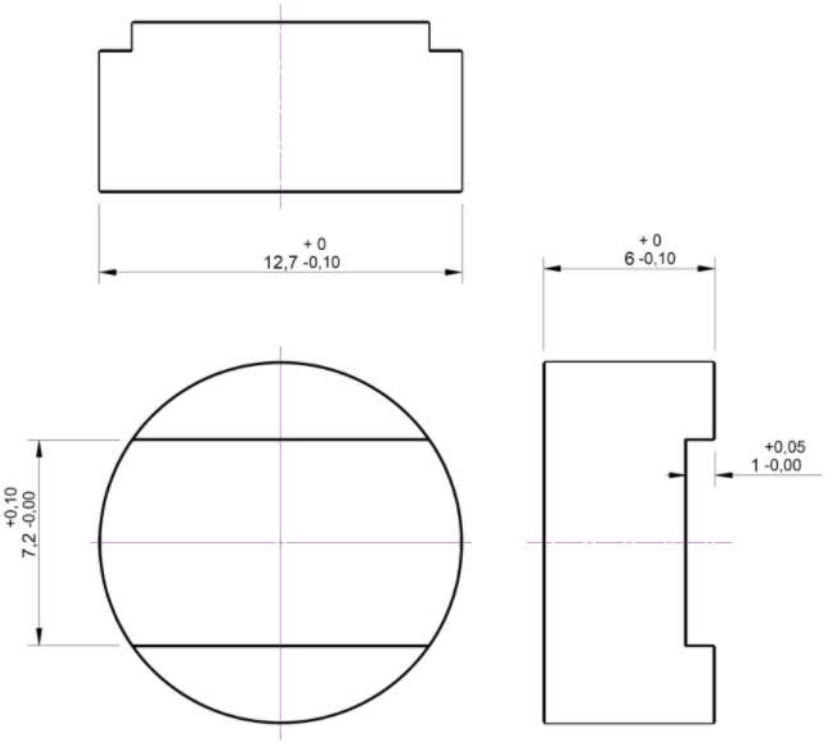
The SAM chip is glued on a gold plated Cu-cylinder with Ø 12.7 mm using a thermal conducting adhesive. The adhesive provides a low thermal resistance between the SAM and the mount.

- The ***standard*** position of the SAM is in the center of the mount → x = 4.0-12.7g-c.
- ***Optional*** the SAM can be soldered at the edge of the mount without extra charges → x = 4.0-12.7g-e.

Center mounted SAM



Edge mounted SAM



Dimensions: